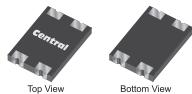


Material Composition Specification

BR DFN Case



Device average mass 61 mg
 Fluctuation margin +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	3.11%	1.9	Si	7440-21-3	3.11%	1.9	31,148
leadframe	FR-4.1	60.49%	36.9	Cu	7440-50-8	30.25%	18.45	302,459
				continuous filament glass fibers	N/A	16.03%	9.78	160,328
				epoxy resin	N/A	11.49%	7.01	114,918
				reactive phosphorous resin	N/A	2.72%	1.66	27,213
die attach	high temperature solder	0.33%	0.2	Pb	7439-92-1	0.29%	0.176	2,885
				Sn	7440-31-5	0.03%	0.02	328
				Ag	7440-22-4	0.01%	0.004	66
encapsulation*	EMC GREEN	34.1%	21	silicon dioxides	14808-60-7	19.48%	11.89	194,836
				bis-phenol epoxy	25036-25-3	14.61%	8.9	146,148
plating	matte tin	1.97%	1.2	Sn	7440-31-5	1.97%	1.2	19,672

*EMC GREEN molding compound is Halogen-Free.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R0 (22-June 2020)